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INTELLECTUAL PROPERTY LAW

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FACSIMILE COVER SHEET

March 1, 2004

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Sender: Quin C. Hoellwarth, Reg. No. 45,738

Re: Request for Corrected Filing Receipt
Application No. 10/702,682
Attorney Docket No. LAM1P131C2

Pages Including Cover Sheet(s): 4

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Hao et al.

Attorney Docket No.: LAM1P131C2

Application No.: 10/702,682

Examiner: Unassigned

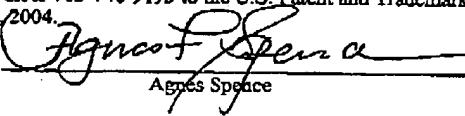
Filed: November 5, 2003

Group: Unassigned

**Title: LINEAR DRIVE SYSTEM FOR USE IN A
PLASMA PROCESSING SYSTEM****CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being transmitted by facsimile to fax number 703-746-9195 to the U.S. Patent and Trademark Office on March 1, 2004.

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REQUEST FOR CORRECTED FILING RECEIPT

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Sir:

Enclosed is a copy of the Filing Receipt for the above-identified patent application. Please reprint the Filing Receipt as follows and mail the corrected copy to the undersigned.

**Change the Domestic Priority data as claimed by applicant to add
"which is a CON of 09/474,843 12/30/99 PAT 6,350,317"**

Attached is the first page of the patent with the correct priority data to illustrate the correct priority. The Commissioner is authorized to charge any fees that may be due to Deposit Account 500388 (Order No. LAM1P131C2).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP



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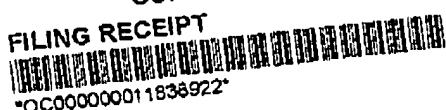
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APPL NO.	FILING OR 371 (C) DATE	ART UNIT	FIL FEE RECD	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/702,682	11/05/2003	1763	860	LAM1P131C2	7	25	3

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BEYER WEAVER & THOMAS LLP
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CONFIRMATION NO. 1118

FILING RECEIPT



OC000000011838922*

Date Mailed: 02/05/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Fangli Hao, Cupertino, CA;
Keith Dawson, Livermore, CA;
Eric H. Lenz, Pleasanton, CA;

Domestic Priority data as claimed by applicant

This application is a CON of 10/012,265 11/05/2001 PAT 6,669,811*

(*) Data provided by applicant is not consistent with PTO records

which is a CON of 09/474,843 12/30/99 PAT 6,350,317

Foreign Applications

If Required, Foreign Filing License Granted: 02/05/2004

Projected Publication Date: 05/13/2004

Non-Publication Request: No

Early Publication Request: No

Title

Linear drive system for use in a plasma processing system

COPY

**LINEAR DRIVE SYSTEM FOR USE IN A PLASMA
PROCESSING SYSTEM**

By Inventors:

Fangli Hao

Keith Dawson

Eric Lenz

Cross Reference to Related Application

[0001] This application is a continuation of U.S. Patent Application No. 10/012,265, filed on November 15, 2001, which is a continuation of U.S. Patent No. 6,350,317 issued February 26, 2002 and which is herein incorporated by reference.

Background of the Invention

[0002] The present invention relates to apparatuses and methods for processing substrates such as semiconductor substrates for use in IC fabrication or panels (e.g., glass, plastic, or the like) for use in flat panel display applications. More particularly, the present invention relates to improved methods and apparatuses for moving components associated with processing a substrate.

[0003] Plasma processing systems have been around for some time. Over the years, plasma processing systems utilizing inductively coupled plasma sources, electron cyclotron resonance (ECR) sources, capacitive sources, and the like, have been introduced and employed to various degrees to process semiconductor substrates and display panels. In a typical plasma processing application, the processing source gases (such as the etchant gases or the deposition source gases) are introduced into a process chamber. Energy is then provided to ignite a plasma in the processing source gases. After the plasma is ignited, it is sustained with additional energy, which may be coupled to the plasma in various well-known ways, e.g., capacitively, inductively,